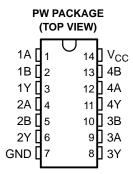
SCLS481B-MAY 2003-REVISED JANUARY 2006

FEATURES

- Controlled Baseline
 - One Assembly/Test Site, One Fabrication Site
- Extended Temperature Performance of -55°C to 125°C
- Enhanced Diminishing Manufacturing Sources (DMS) Support
- Enhanced Product-Change Notification
- Qualification Pedigree (1)
- Typical V_{OLP} (Output Ground Bounce)
 <0.8 V at V_{CC} = 3.3 V, T_A = 25°C
- Typical V_{OHV} (Output V_{OH} Undershoot)
 >2.3 V at V_{CC} = 3.3 V, T_A = 25°C
- Supports Mixed-Mode Voltage Operation on All Ports
- I_{off} Supports Partial-Power-Down Mode Operation
- (1) Component qualification in accordance with JEDEC and industry standards to ensure reliable operation over an extended temperature range. This includes, but is not limited to, Highly Accelerated Stress Test (HAST) or biased 85/85, temperature cycle, autoclave or unbiased HAST, electromigration, bond intermetallic life, and mold compound life. Such qualification testing should not be viewed as justifying use of this component beyond specified performance and environmental limits.

- Latch-Up Performance Exceeds 250 mA Per JESD 17
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)



DESCRIPTION/ORDERING INFORMATION

This quadruple 2-input positive-AND gate is designed for 2-V to 5.5-V V_{CC} operation.

The SN74LV08A-EP performs the Boolean function $Y = A \cdot B$ or $Y = \overline{A + B}$ in positive logic.

This device is fully specified for partial-power-down applications using I_{off}. The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

ORDERING INFORMATION

T _A	PACK	AGE ⁽¹⁾	ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 105°C	TSSOP – PW	Tape and reel	SN74LV08ATPWREP	LV08AEP
−55°C to 125°C	TSSOP - PW	Tape and reel	SN74LV08AMPWREP	LV08AEP

(1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE (EACH GATE)

INP	JTS	OUTPUT
Α	В	Y
Н	Н	Н
L	Χ	L
X	L	L



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LOGIC DIAGRAM, EACH GATE (POSITIVE LOGIC)



Absolute Maximum Ratings(1)

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
V_{CC}	Supply voltage range		-0.5	7	V
VI	Input voltage range ⁽²⁾		-0.5	7	V
Vo	Voltage range applied to any output in the high	h-impedance or power-off state ⁽²⁾	-0.5	7	V
Vo	Output voltage range ⁽²⁾⁽³⁾	Output voltage range ⁽²⁾⁽³⁾			
I _{IK}	Input clamp current	V ₁ < 0		-20	mA
I _{OK}	Output clamp current	V _O < 0		-50	mA
Io	Continuous output current	$V_O = 0$ to V_{CC}		±25	mA
	Continuous current through V _{CC} or GND			±50	mA
θ_{JA}	Package thermal impedance ⁽⁴⁾		113	°C/W	
T _{stg}	Storage temperature range		-65	150	°C

⁽¹⁾ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

⁽²⁾ The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.

⁽³⁾ This value is limited to 5.5 V maximum.

⁽⁴⁾ The package thermal impedance is calculated in accordance with JESD 51-7.



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Recommended Operating Conditions(1)

			MIN	MAX	UNIT		
V _{CC}	Supply voltage		2	5.5	V		
		V _{CC} = 2 V	1.5				
1/	High level input valtage	V _{CC} = 2.3 V to 2.7 V	$V_{CC} \times 0.7$		V		
V_{IH}	High-level input voltage	V _{CC} = 3 V to 3.6 V	$V_{CC} \times 0.7$		V		
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$	$V_{CC} \times 0.7$				
		V _{CC} = 2 V		0.5			
17	Lour loval input voltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		$V_{CC} \times 0.3$	V		
V_{IL}	Low-level input voltage	V _{CC} = 3 V to 3.6 V		$V_{CC} \times 0.3$			
		V _{CC} = 4.5 V to 5.5 V		$V_{CC} \times 0.3$			
VI	Input voltage		0	5.5	V		
Vo	Output voltage		0	V _{CC}	V		
		V _{CC} = 2 V		-50	μΑ		
	High lovel output ourrent	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		-2			
I _{OH}	High-level output current	$V_{CC} = 3 \text{ V to } 3.6 \text{ V}$		-6	mA		
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$		-12			
		V _{CC} = 2 V		50	μΑ		
	Low lovel output ourrent	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		2			
I _{OL}	Low-level output current	V _{CC} = 3 V to 3.6 V		6	mA		
		V _{CC} = 4.5 V to 5.5 V					
		V _{CC} = 2.3 V to 2.7 V		200			
$\Delta t/\Delta v$	Input transition rise or fall rate	V _{CC} = 3 V to 3.6 V		100	ns/V		
		V _{CC} = 4.5 V to 5.5 V		20			
т	Operating free air temperature	SN74LV08AM	-55	125	- °C		
T_A	Operating free-air temperature	SN74LV08AT	-40	105			

⁽¹⁾ All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implication of Slow or Floating CMOS Inputs, literature number SCBA004.

Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V _{cc}	MIN	TYP	MAX	UNIT
	$I_{OH} = -50 \mu A$	2 V to 5.5 V	V _{CC} - 0.1			
V	$I_{OH} = -2 \text{ mA}$	2.3 V	2			V
V_{OH}	$I_{OH} = -6 \text{ mA}$	3 V	2.48			V
	I _{OH} = -12 mA	4.5 V	3.8			
	I _{OL} = 50 μA	2 V to 5.5 V			0.1	
V	I _{OL} = 2 mA	2.3 V	0.4	V		
VOL	I _{OL} = 6 mA	3 V			0.44	V
V _{OL}	I _{OL} = 12 mA	4.5 V			0.55	
I _I	V _I = 5.5 V or GND	0 to 5.5 V			±1	μΑ
I _{CC}	$V_I = V_{CC}$ or GND, $I_O = 0$	5.5 V			20	μΑ
I _{off}	V_I or $V_O = 0$ to 5.5 V	0			5	μΑ
	V V CND	3.3 V		3.3		
C _i	$V_I = V_{CC}$ or GND	5 V		3.3		pF

SN74LV08A-EP QUADRUPLE 2-INPUT POSITIVE-AND GATE





Switching Characteristics

over recommended operating free-air temperature range, V_{CC} = 3.3 V \pm 0.3 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	то	LOAD	T,	չ = 25°C		MIN	MAX	UNIT
PARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	IVIIIV	IVIAA	UNIT
t _{pd}	A or B	Y	C _L = 50 pF		7.5	12.3	1	16	ns

Switching Characteristics

over recommended operating free-air temperature range, V_{CC} = 5 V \pm 0.5 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	то	LOAD	T,	√ = 25°C		MIN	MAX	UNIT
FARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	IVIIIV	IVIAA	UNIT
t _{pd}	A or B	Υ	$C_{L} = 50 \text{ pF}$		5.5	7.9	1	12	ns

Noise Characteristics⁽¹⁾

 $V_{CC} = 3.3 \text{ V}, C_L = 50 \text{ pF}, T_A = 25^{\circ}\text{C}$

		MIN	TYP	MAX	UNIT
$V_{OL(P)}$	Quiet output, maximum dynamic V _{OL}		0.2	8.0	V
$V_{OL(V)}$	Quiet output, minimum dynamic V _{OL}		-0.1	-0.8	V
$V_{OH(V)}$	Quiet output, minimum dynamic V _{OH}		3.1		V
$V_{IH(D)}$	High-level dynamic input voltage	2.31			V
$V_{IL(D)}$	Low-level dynamic input voltage			0.99	V

⁽¹⁾ Characteristics are for surface-mount packages only.

Operating Characteristics

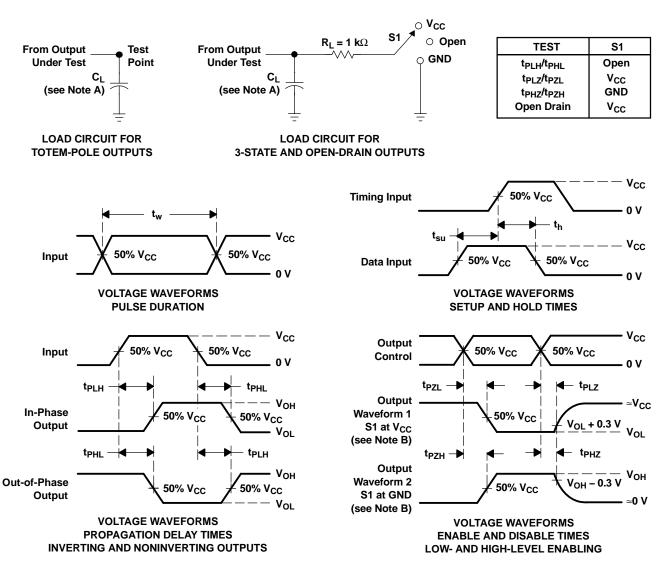
 $T_A = 25^{\circ}C$

	PARAMETER	TEST CONDITIONS	V _{cc}	TYP	UNIT
C_{pd}	Down dissination conscitones	C 50 pF f 10 MHz	3.3 V	8	pF
	Power dissipation capacitance	$C_L = 50 \text{ pF}, f = 10 \text{ MHz}$	5 V	10	





PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, $Z_O = 50 \Omega$, $t_r \leq$ 3 ns, $t_f \leq$ 3 ns.
- D. The outputs are measured one at a time, with one input transition per measurement.
- E. t_{PLZ} and t_{PHZ} are the same as t_{dis}.
- F. t_{PZL} and t_{PZH} are the same as t_{en} .
- G. t_{PHL} and t_{PLH} are the same as t_{pd} .
- H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuits and Voltage Waveforms



PACKAGE OPTION ADDENDUM

10-Dec-2020

PACKAGING INFORMATION

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Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
SN74LV08AMPWREP	ACTIVE	TSSOP	PW	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	LV08AEP	Samples
SN74LV08ATPWREP	ACTIVE	TSSOP	PW	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 105	LV08AEP	Samples
V62/03660-01XE	ACTIVE	TSSOP	PW	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 105	LV08AEP	Samples
V62/03660-02XE	ACTIVE	TSSOP	PW	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	LV08AEP	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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PACKAGE OPTION ADDENDUM

10-Dec-2020

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OTHER QUALIFIED VERSIONS OF SN74LV08A-EP:

Catalog: SN74LV08A

Automotive: SN74LV08A-Q1

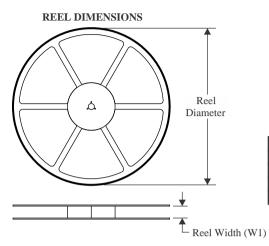
NOTE: Qualified Version Definitions:

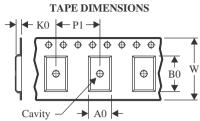
- Catalog TI's standard catalog product
- Automotive Q100 devices qualified for high-reliability automotive applications targeting zero defects

PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

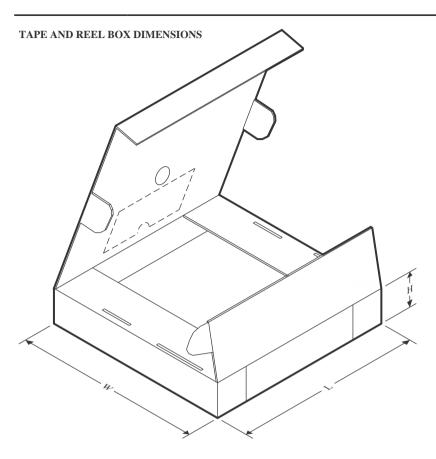
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LV08AMPWREP	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74LV08ATPWREP	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

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*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LV08AMPWREP	TSSOP	PW	14	2000	356.0	356.0	35.0
SN74LV08ATPWREP	TSSOP	PW	14	2000	356.0	356.0	35.0

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